

MiniSKiiP® 3

Sixpack

SKiiP 39AC12T4V21

Features*

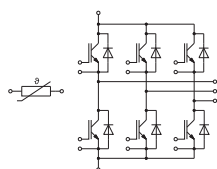
- Trench 4 IGBTs
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532
- Insulated by Si₃N₄ (Silicon Nitride) AMB (Active Metal Brazed) ceramic substrate for optimized thermal performance

Typical Applications

- Inverter up to 50 kVA
- Typical motor power 30 kW

Remarks

- Max. case temperature limited to T_C=125°C
- Product reliability results valid for T_j≤150°C (recommended T_{j,op}=-40...+150°C)
- For short circuit: Soft R_{Goff} recommended
- MiniSKiiP “Technical Explanations” and “Mounting Instructions” are part of the data sheet. Please refer to both documents for further information.



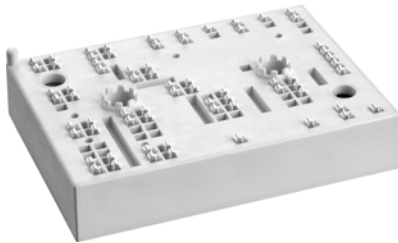
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Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V _{CES}	T _J = 25 °C		1200	V
I _C	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	189	A
	T _J = 175 °C	T _s = 70 °C	154	A
I _C	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	249	A
	T _J = 175 °C	T _s = 70 °C	204	A
I _{Cnom}			150	A
I _{CRM}			450	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 800 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _J = 150 °C	10	μs
T _J			-40 ... 175	°C
Inverse - Diode				
V _{RRM}	T _J = 25 °C		1200	V
I _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	149	A
	T _J = 175 °C	T _s = 70 °C	118	A
I _F	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	221	A
	T _J = 175 °C	T _s = 70 °C	177	A
I _{FRM}			450	A
I _{FSM}	t _p = 10 ms, sin 180°, T _J = 150 °C		900	A
T _J			-40 ... 175	°C
Module				
I _{t(RMS)}	T _{terminal} = 80 °C, 20 A per spring		160	A
T _{stg}	module without TIM		-40 ... 125	°C
V _{isol}	AC sinus 50 Hz, t = 1 min		2500	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
Inverter - IGBT					
V _{CE(sat)}	I _C = 150 A V _{GE} = 15 V chipelevel	T _j = 25 °C	1.85	2.10	V
		T _j = 150 °C	2.25	2.45	V
V _{CE0}	chipelevel	T _j = 25 °C	0.80	0.90	V
		T _j = 150 °C	0.70	0.80	V
r _{CE}	V _{GE} = 15 V chipelevel	T _j = 25 °C	7.0	8.0	mΩ
		T _j = 150 °C	10	11	mΩ
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 6 mA	5	5.8	6.5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = 1200 V, T _j = 25 °C			1.5	mA
C _{ies}	V _{CE} = 25 V	f = 1 MHz	8.80		nF
C _{oes}	V _{GE} = 0 V	f = 1 MHz	0.58		nF
C _{res}		f = 1 MHz	0.47		nF
Q _G	V _{GE} = - 8 V...+ 15 V		850		nC
R _{Gint}	T _j = 25 °C		5.0		Ω
t _{d(on)}	V _{CC} = 600 V	T _j = 150 °C	165		ns
t _r	I _C = 150 A	T _j = 150 °C	50		ns
E _{on}	R _{G on} = 1 Ω	T _j = 150 °C	22.5		mJ
t _{d(off)}	R _{G off} = 1 Ω	T _j = 150 °C	390		ns
t _f	di/dt _{on} = 2840 A/μs di/dt _{off} = 1880 A/μs	T _j = 150 °C	80		ns
E _{off}	V _{GE} = +15/-15 V	T _j = 150 °C	14		mJ
R _{th(j-s)}	per IGBT, λ _{paste} =0.8 W/(mK)		0.26		K/W
R _{th(j-s)}	per IGBT, λ _{paste} =2.5 W/(mK)		0.16		K/W



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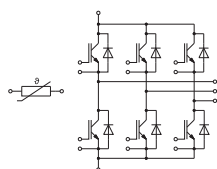
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- Max. case temperature limited to $T_C=125^{\circ}\text{C}$
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- For short circuit: Soft R_{Goff} recommended
- MiniSKiiP "Technical Explanations" and "Mounting Instructions" are part of the data sheet. Please refer to both documents for further information.

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse - Diode						
V _F = V _{EC}	I _F = 150 A	T _j = 25 °C		2.14	2.46	V
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.07	2.38	V
V _{F0}	chiplevel	T _j = 25 °C		1.30	1.50	V
		T _j = 150 °C		0.90	1.10	V
r _F	chiplevel	T _j = 25 °C		5.6	6.4	mΩ
		T _j = 150 °C		7.8	8.5	mΩ
I _{RRM}	I _F = 150 A	T _j = 150 °C		188		A
Q _{rr}	di/dt _{off} = 4020 A/μs	T _j = 150 °C		27		μC
E _{rr}	V _{GE} = +15/-15 V	T _j = 150 °C		11.4		mJ
	V _{CC} = 600 V					
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(mK)			0.45		K/W
R _{th(j-s)}	per Diode, λ _{paste} =2.5 W/(mK)			0.24		K/W
Module						
L _{CE}				-		nH
M _s	to heat sink		2		2.5	Nm
w				82		g
Temperature Sensor						
R ₁₀₀	T _r =100°C (R ₂₅ =1000Ω)			1670 ± 3%		Ω
R _(T)	R _(T) =1000Ω[1+A(T-25°C)+B(T-25°C) ²] , A = 7.635*10 ⁻³ °C ⁻¹ , B = 1.731*10 ⁻⁵ °C ⁻²					



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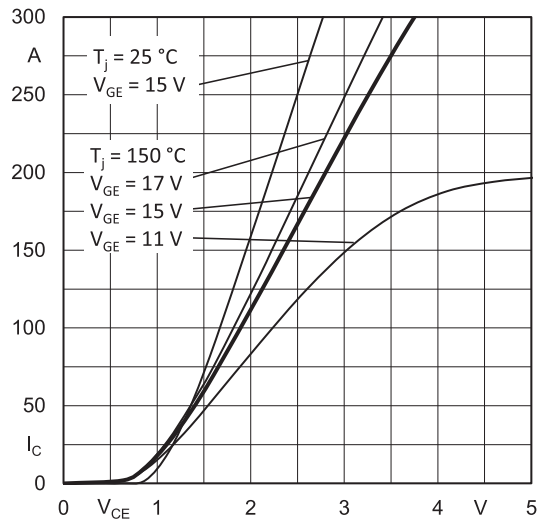


Fig. 1: Typ. output characteristic

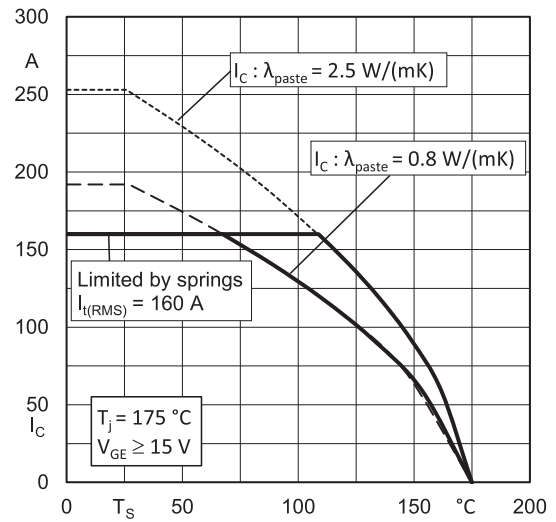


Fig. 2: Rated current vs. temperature $I_C = f(T_S)$

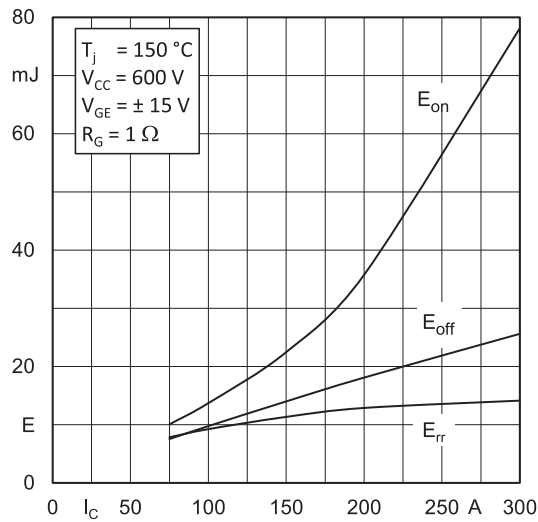


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

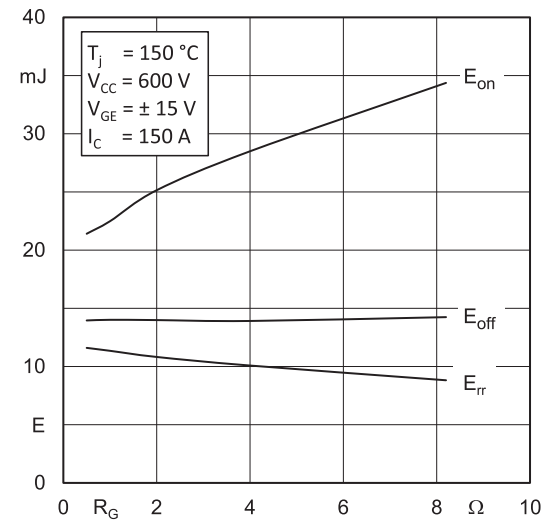


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

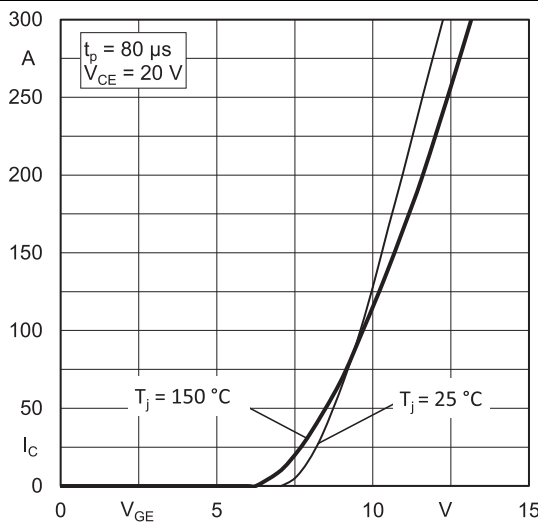


Fig. 5: Typ. transfer characteristic

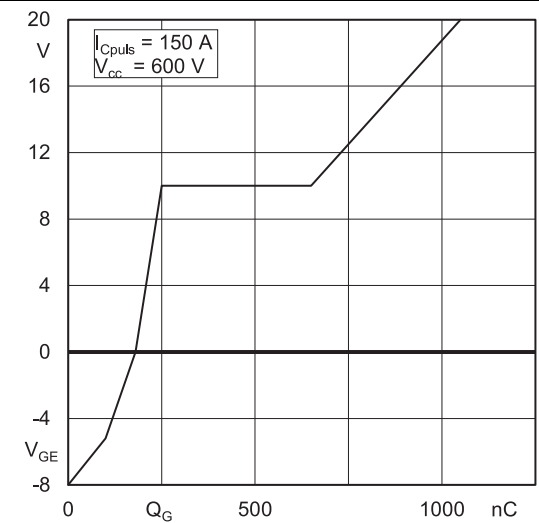


Fig. 6: Typ. gate charge characteristic

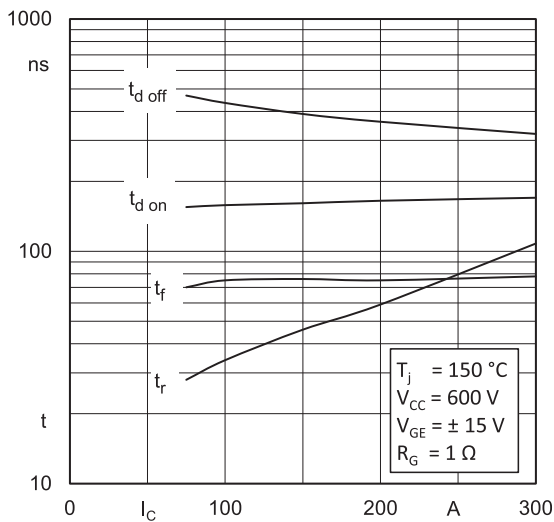


Fig. 7: Typ. switching times vs. I_C

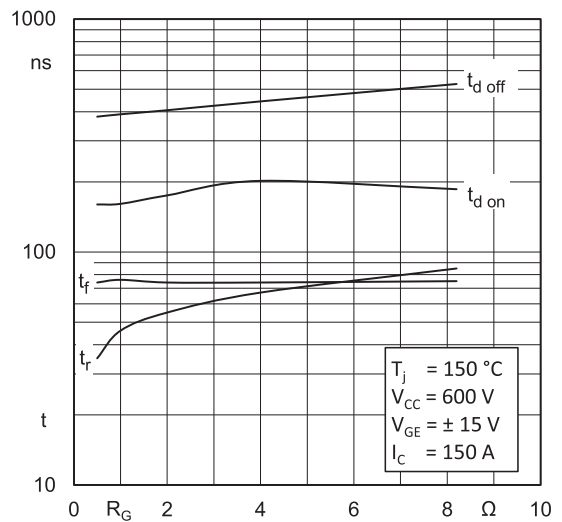


Fig. 8: Typ. switching times vs. gate resistor R_G

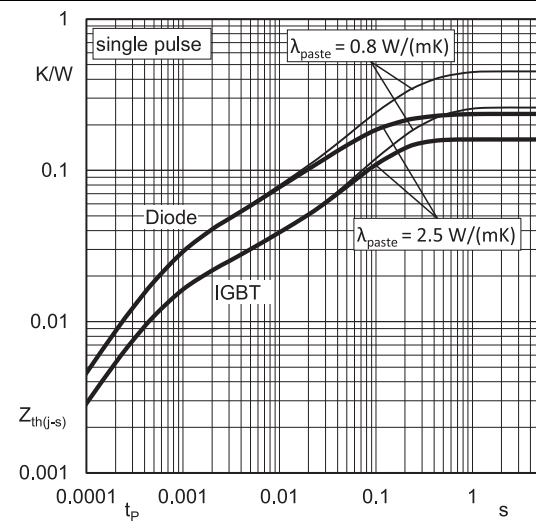


Fig. 9: Typ. transient thermal impedance

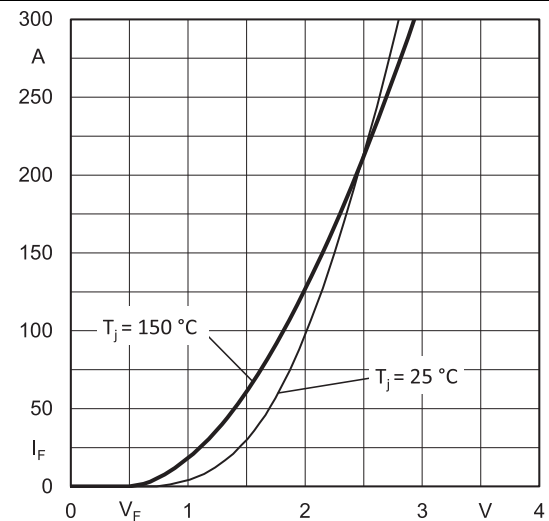


Fig. 10: Typ. CAL diode forward characteristic

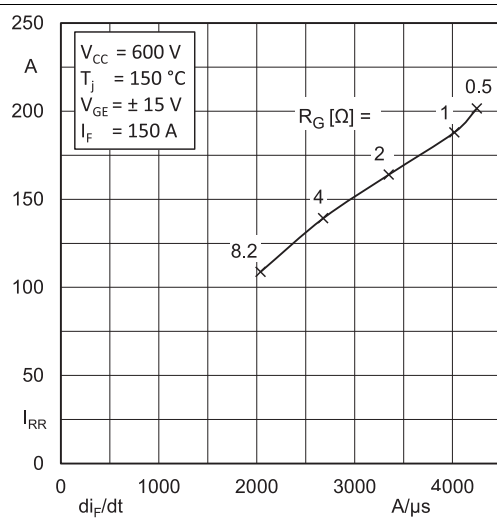


Fig. 11: Typ. CAL diode peak reverse recovery current

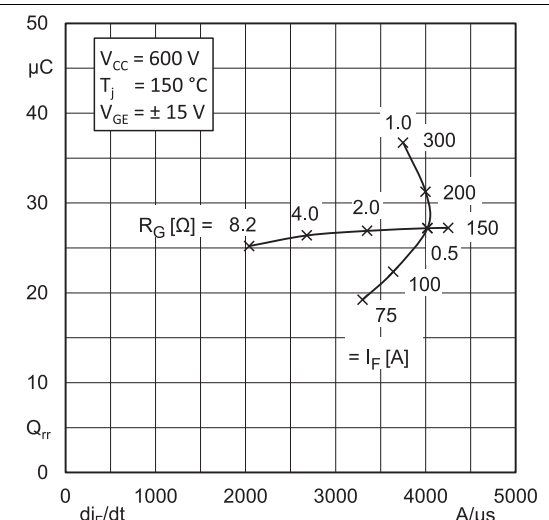
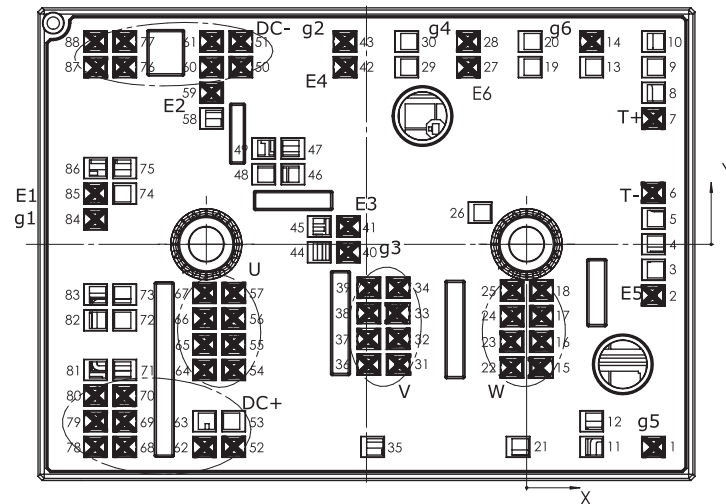


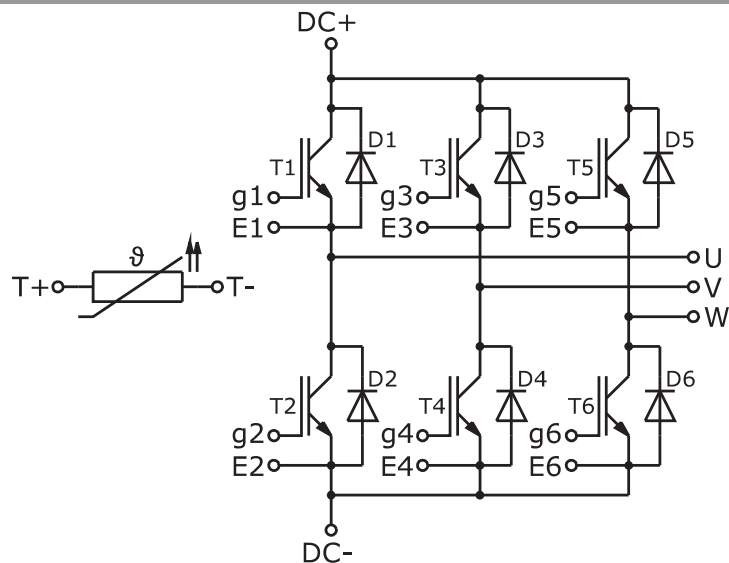
Fig. 12: Typ. CAL diode recovery charge

Pin out											
Pin	X	Y	Function	Pin	X	Y	Function	Pin	X	Y	Function
1	15,83	-25,30	g5	31	-16,05	-15,02	V	61	-39,33	25,30	DC-
2	15,83	-6,40	E5	32	-16,05	-11,82	V	62	-40,23	-25,30	DC+
3	15,83	-3,20		33	-16,05	-8,62	V	63	-40,23	-22,10	
4	15,83	0		34	-16,05	-5,42	V	64	-40,23	-15,70	U
5	15,83	3,20		35	-19,23	-25,30		65	-40,23	-12,50	U
6	15,83	6,40	T-	36	-19,70	-15,02	V	66	-40,23	-9,30	U
7	15,83	15,70	T+	37	-19,70	-11,82	V	67	-40,23	-6,10	U
8	15,83	18,90		38	-19,70	-8,62	V	68	-50,18	-25,30	DC+
9	15,83	22,10		39	-19,70	-5,42	V	69	-50,18	-22,10	DC+
10	15,83	25,30		40	-22,26	-1,00	g3	70	-50,18	-18,90	DC+
11	8,13	-25,30		41	-22,26	2,20	E3	71	-50,18	-15,70	
12	8,13	-22,10		42	-22,68	22,10	E4	72	-50,18	-9,50	
13	8,13	22,10		43	-22,68	25,30	g2	73	-50,18	-6,30	
14	8,13	25,30	g6	44	-25,91	-1,00		74	-50,18	6,30	
15	1,83	-15,39	W	45	-25,91	2,20		75	-50,18	9,50	
16	1,83	-12,19	W	46	-29,18	8,74		76	-50,18	22,10	DC-
17	1,83	-8,99	W	47	-29,18	11,94		77	-50,18	25,30	DC-
18	1,83	-5,79	W	48	-32,83	8,74		78	-53,83	-25,30	DC+
19	0,43	22,10		49	-32,83	11,94		79	-53,83	-22,10	DC+
20	0,43	25,30		50	-35,68	22,10	DC-	80	-53,83	-18,90	DC+
21	-1,08	-25,30		51	-35,68	25,30	DC-	81	-53,83	-15,70	
22	-1,83	-15,39	W	52	-36,58	-25,30	DC+	82	-53,83	-9,50	
23	-1,83	-12,19	W	53	-36,58	-22,10		83	-53,83	-6,30	
24	-1,83	-8,99	W	54	-36,58	-15,70	U	84	-53,83	3,10	g1
25	-1,83	-5,79	W	55	-36,58	-12,50	U	85	-53,83	6,30	E1
26	-5,83	3,95		56	-36,58	-9,30	U	86	-53,83	9,50	
27	-7,28	22,10	E6	57	-36,58	-6,10	U	87	-53,83	22,10	DC-
28	-7,28	25,30	g4	58	-39,33	15,70		88	-53,83	25,30	DC-
29	-14,98	22,10		59	-39,33	18,90	E2				
30	-14,98	25,30		60	-39,33	22,10	DC-				

all values in mm



Pinout and Dimensions



Pinout

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

***IMPORTANT INFORMATION AND WARNINGS**

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